GAP-151R-S8-SOLO

1U Rugged Server- Rear I/O & Rear Power supply Single Socket 5th/4th Gen Intel[®] Xeon[®] Scalable Processors





GAP is a product family of rugged aluminum servers and workstations designed for applications that require robust and qualified MIL-GRADE equipment, suitable for operations in critical environments.

1U PLATFORM

510 MM

1 CPU 2TB

UP TO 9
HOT SWAP SSD

J/O BOARDS

GAP-151R-S8-SOLO rugged servers are powered by dual-socket 5th Gen Intel® Xeon® / 4th Gen Intel® Xeon® Scalable processors known for their robust architecture with enhanced AI acceleration and advanced security capabilities. Offering improved performance and efficiency, they are tailored to meet the demanding requirements of modern computing environments, making them an ideal choice for mission-critical tasks and high-performance applications.

GAP-151R-S8-SOLO are designed for 19" rackmounting and have a 1U chassis with a total overall depth of 540mm. Notably, the 19" front brackets of the chassis are strategically positioned in a backward orientation, reducing the required cabinet space to just 510mm once fully installed.

The rear I/O and rear power supply configuration offers versatile storage options, including an on board M.2 NVME SSD and either up to three removable 2.5" SAS SSD, six removable U.2 NVMe SSD or up to nine removable 2.5" SATA SSDs.

Moreover, this rugged server can accommodate up to two full-height full-lenght PCIe cards, in addition to one low-profile card.

For enhanced protection against shocks and vibrations, additional boards can be supplied with a dedicated retainer kit, ensuring optimal safety even during transport.

GAP servers are designed to meet MIL-STD-810F standards for temperature and shocks, as well as MIL-STD-167-1A standards for vibrations. Additionally, they can optionally conform to MIL-STD-461 standards for EMI/EMC. Upon request, MIL-GRADE connectors can be provided for the I/O connectors and power supply inputs.

All units are shipped with an inventory list to guarantee configuration control and reproducibility over time. Additionally, upon request, all server configurations can undergo specific thermal or mechanical environmental stress tests.



Technical Specifications



System	5 th Gen Intel [®] Xeon [®] / 4 th Gen Intel [®] Xeon [®]	Mecha	
CPU	Scalable processors, Single Socket LGA-4677 (Socket E) supported, CPU TDP Up to 205W TDP	Dimensio Material	
Memory	Up to 2TB ECC RDIMM, DDR5-4800MT/s in 8 DIMM slots	Colour	
Chipset	Intel® C741	Mounting	
Graphics	1 Aspeed AST2600 BMC port		
Network Connectivity	1x Dedicated IPMI LAN port 2x 10GbE with RJ45 connectors	Configura	
,	On Board: 1x M.2 NVMe; M-Key, 2280/22110 2x SATA Disk on Module	Front Par Leds / Bu Connecto	
Storage	Removable:	Fans	
	Up to 3x 2.5" SAS SSD or Up to 6x U.2 NVMe SSD or Up to 9x 2.5" SATA SSD	Enviro	
ТРМ	1x TPM Header	Operating	
Motherboard I/O shield	1x VGA, 2x USB 3.0, 2x USB 2.0, 2x 10GbE, 1x IPMI, 1x COM (available on the rear panel)	Temperat Storage Temperat	
Expansion slots	2x PCIe 5.0 x16 slot FHFL 1x PCIe 5.0 x16 slot low profile		
Operative Systems	Windows® 11 IoT Enterprise, Windows® 10 IoT Enterprise LTSC, Windows® Server	Humidity	
	2022, Windows® Server 2019, Linux	Operating Vibration	
IPMI	IPMI2.0, SPM, Watchdog; SNMP and e-mail alarms and notifications	Not Oper	
	Monitoring, control and management functions (fan speed, temperature,	Vibration	
Remote Monitoring	voltage, redundant power failure, power consumption, disk health, RAID health, and memory health)	Operating Shocks	

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P	ow	er	Su	g	pľ	٧

Dawer Cumply	AC or DC Redundant Power Supply -			
Power Supply	Optional AC Single			

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M	e	Cl	าล	n	ica

Dimensions	483 x 44 x 510 mm 540 mm full depth (W x H x D)
Material	Aluminum with surface passivation treatment
Colour	Black / RAL 9005 - Powder Coating
Mounting	1U 19" rackmount chassis Optional Telescopic slides
Configuration	Rear I/O - Rear Power Supply
Front Panel Leds / Buttons / Connectors	Power On/Off button with LED Reset button with LED 2x USB 3.0
Fans	6x internal PWM fans

Environmental - (Design to meet)

Operating Temperatures	0°C to +50°C MIL-STD-810H, Method 501.7 & 502.7 -20°C to +60°C (depending on configuration)
Storage Temperature	-40°C to +70°C MIL-STD-810H, Method 501.7 & 502.7
Humidity	5% – 95% non-condensing MIL-STD-810H 507.6
Operating Vibrations	MIL-STD-167-1A, Type I
Not Operating Vibrations	1.17 Grms, 5-500 Hz MIL-STD-810H, Method 514.8
Operating Shocks	20g / 11ms – half sine MIL-STD-810G, Method 516.7
EMC	Directive 2014/35/UE-LVD Directive 2014/30/UE-EMC Directive 2011/65/UE - RoHS Regulation EC No 1907/2006 MIL-STD-461G (on request)

GAP servers and workstations are designed in accordance with the environmental specifications indicated. Some parameters depend on the configuration. Equipment may be subjected to dedicated test profiles.